

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	I <sub>PP</sub>	6.5	A	8/20μs, From CH to GND
Peak Pulse Current	I <sub>PP</sub>	6.5	A	8/20μs, From GND to CH
Peak Pulse Power	P <sub>PP</sub>	60	W	8/20μs, From CH to GND
ESD Protection – Contact Discharge	V <sub>ESD_Contact</sub>	±18	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V <sub>ESD_Air</sub>	±20	kV	Standard IEC 61000-4-2
Operating Temperature	T <sub>OP</sub>	-55 to +85	°C	—
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C	—

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P <sub>D</sub>	200	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	R <sub>θJA</sub>	625	°C/W

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V <sub>RWM</sub>	—	—	5.5	V	—
Channel Leakage Current (Note 6, 7)	I <sub>R</sub>	—	1	10	nA	V <sub>R</sub> = 2.5V
Reverse Breakdown Voltage	V <sub>BR</sub>	7.0	—	9.5	V	I <sub>R</sub> = 1mA, from CH to GND
Clamping Voltage, Positive Transients	V <sub>CL1</sub>	—	6.8	—	V	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs
Clamping Voltage, Positive Transients	V <sub>CL1</sub>	—	9	—	V	I <sub>PP</sub> = 5A, t <sub>p</sub> = 8/20μs
Clamping Voltage, Negative Transients	V <sub>CL2</sub>	—	1.5	—	V	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs
Forward Voltage	V <sub>F</sub>	—	0.7	—	V	I <sub>F</sub> = 1mA, GND to CH
Dynamic Resistance	R <sub>DIFF</sub>	—	0.4	—	Ω	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs, CH to GND
Dynamic Resistance	R <sub>DIFF-R</sub>	—	0.45	—	Ω	TLP, 20A, t <sub>p</sub> = 100 ns, CH to GND
Dynamic Resistance	R <sub>DIFF-F</sub>	—	0.2	—	Ω	TLP, 20A, t <sub>p</sub> = 100 ns, GND to CH
CH to GND Capacitance	C <sub>(CH-GND)</sub>	—	0.75	—	pF	V <sub>(CH-GND)</sub> = 0V, f = 1MHz
		—	0.65	0.9	pF	V <sub>(CH-GND)</sub> = 2.5V, f = 1MHz
Delta C <sub>CH</sub>	C <sub>CHMAX</sub> -C <sub>CHMIN</sub>	—	0.04	—	pF	C <sub>CHMAX</sub> -C <sub>CHMIN</sub>

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.

6. Short duration pulse test used to minimize self-heating effect.

7. Measured from pin 1, 2, 4 and 5 to GND.

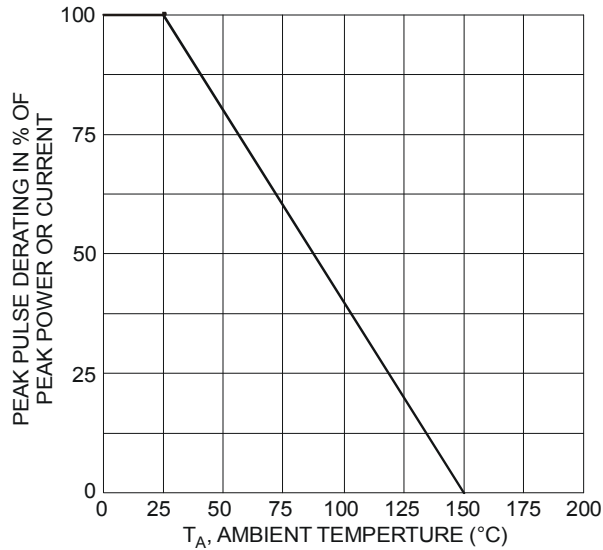


Figure 1 Pulse Derating Curve

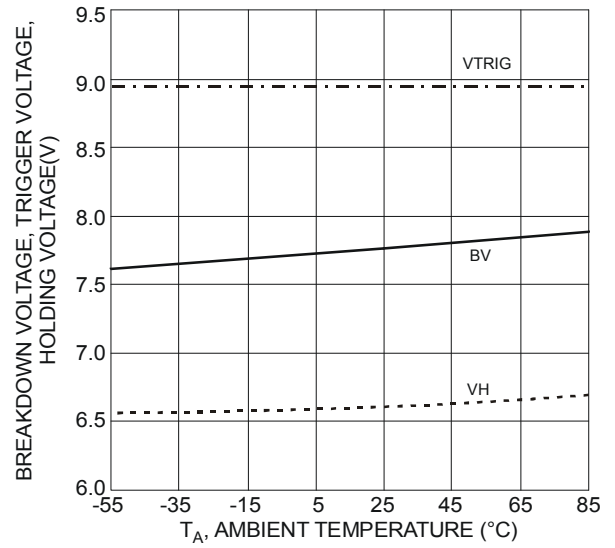


Figure 2 BV, Trigger Voltage, Holding Voltage vs. Ambient Temperature

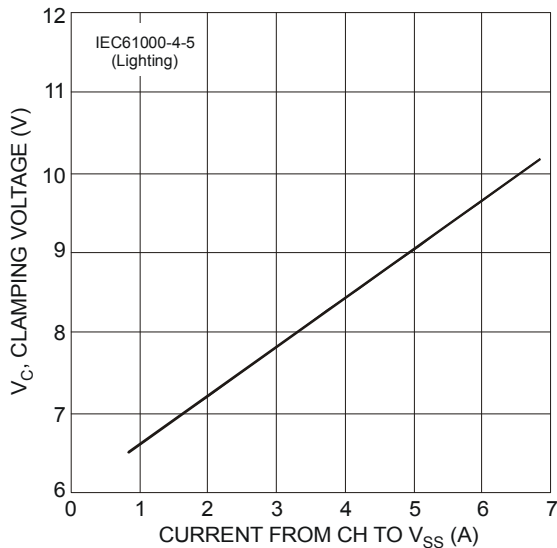


Figure 3 Clamping Voltage Characteristic

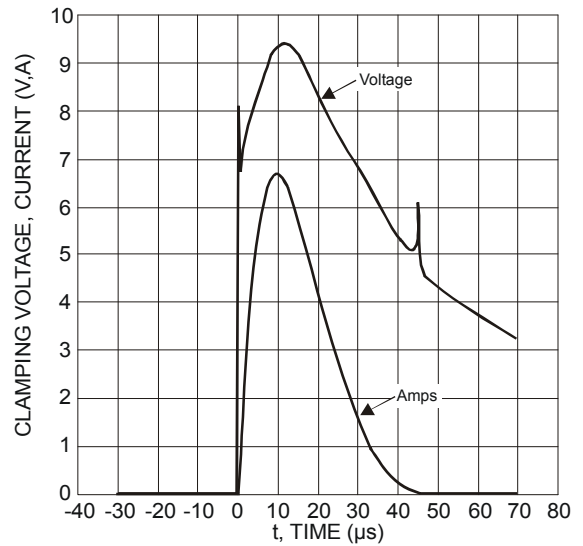


Figure 4 Waveform of Clamping Voltage, Current vs. Time (8/20μs, CH to  $V_{SS}$ )

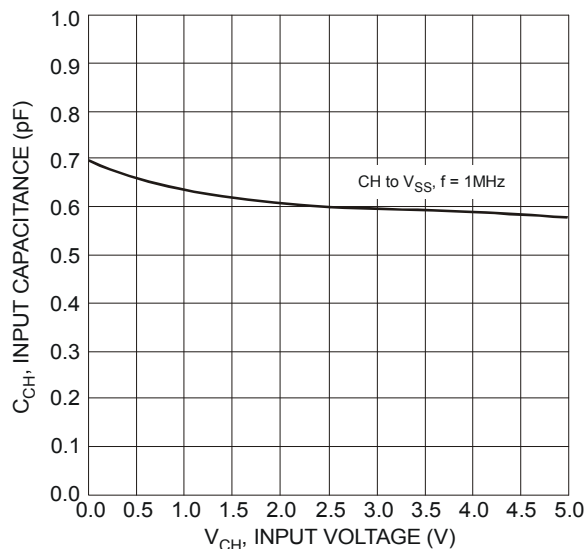


Figure 5 Input Capacitance vs. Input Voltage

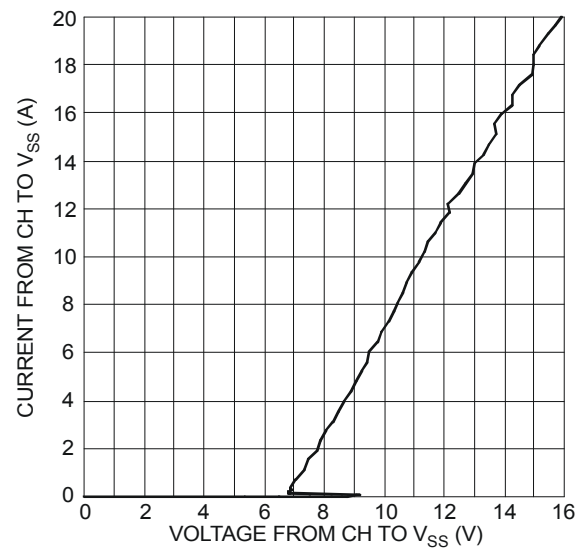
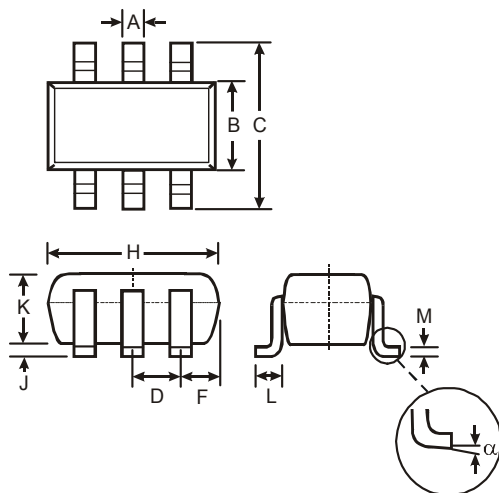


Figure 6 Current vs. Voltage

## Package Outline Dimensions

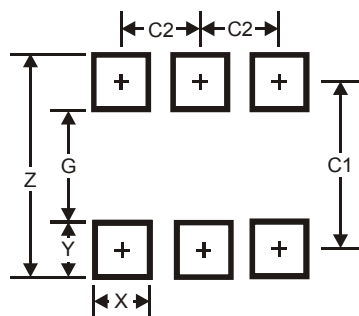
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT363			
Dim	Min	Max	Typ
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

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